

July 2014

RHRG3060_F085 30A, 600V Hyperfast Rectifier

Features

- High Speed Switching (t_{rr}=45ns(Typ.) @ I_F=30A)
- Low Forward Voltage(V_F=1.64V(Typ.) @ I_F=30A)
- · Avalanche Energy Rated
- · AEC-Q101 Qualified

Applications

- · Switching Power Supply
- · Power Switching Circuits
- · Automotive and General Purpose

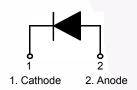
Max Ratings (600V, 30A)

The RHRG3060_F085 is an Hyperfast™ diode with soft recovery characteristics (trr < 45ns). It has half the recovery time of ultrafast diode and is of silicon nitride passivated ion-implanted epitaxial planar construction. This device is intended for use as a freewheeling/clamping diode and rectifier in a variety of automotive switching power supplies and other power switching automotive applications. Its low stored charge and

ing diode and rectifier in a variety of automotive switching power supplies and other power switching automotive applications. Its low stored charge and hyperfast soft recovery minimize ringing and electrical noise in many power switching circuits, thus reducing power loss in the switching transistors.

Pin Assignments





Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter	Ratings	Units	
V_{RRM}	Peak Repetitive Reverse Voltage	600	V	
V _{RWM}	Working Peak Reverse Voltage 600 V			
V _R	DC Blocking Voltage 600			
I _{F(AV)}	Average Rectified Forward Current @ T _C = 25°C	30	Α	
I _{FSM}	Non-repetitive Peak Surge Current (Halfwave 1 Phase 50Hz)	90	Α	
E _{AVL}	Avalanche Energy (1A, 40mH) 20		mJ	
T _J , T _{STG}	Operating Junction and Storage Temperature - 55 to +175 °C		°C	

Thermal Characteristics T_C = 25°C unless otherwise noted

Symbol	Parameter	Max	Units
$R_{\theta JC}$	Maximum Thermal Resistance, Junction to Case	0.66	°C/W
$R_{\theta JA}$	Maximum Thermal Resistance, Junction to Ambient	45	°C/W

Package Marking and Ordering Information

Device Marking Device		Package	Tube	Quantity	
RHRG3060	RHRG3060_F085	TO-247	-	30	

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted

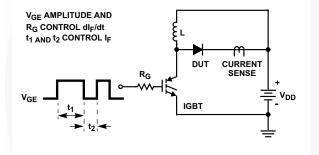
Symbol	Parameter	Conditions		Min.	Тур.	Max	Units
I _R	Instantaneous Reverse Current	V _R = 600V	T _C = 25 °C	-	-	250	uA
			T _C = 175 °C	-	-	1.5	mA
V _{FM} ¹	Instantaneous Forward Voltage	I _F = 30A	T _C = 25 °C T _C = 175 °C	-	1.64 1.24	2.1 1.7	V V
t _{rr} ²	Reverse Recovery Time	I_F =1A, di/dt = 200A/ μ s, V_{CC} = 390V	T _C = 25 °C	-	24	40	ns
		I_F =30A, di/dt = 200A/ μ s, V_{CC} = 390V	T _C = 25 °C T _C = 175 °C	-	33 136	45 -	ns ns
t _a t _b Q _{rr}	Reverse Recovery Time Reverse Recovery Charge	$I_F = 30A$, di/dt = 200A/ μ s, $V_{CC} = 390V$	T _C = 25 °C	- - -	19 14 60	- - -	ns ns nC

Notes:

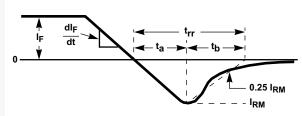
- 1. Pulse : Test Pulse width = 300μs, Duty Cycle = 2%
- 2. Guaranteed by design

Test Circuit and Waveforms

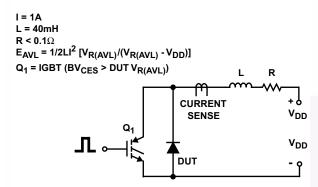
t_{rr} Test Circuit



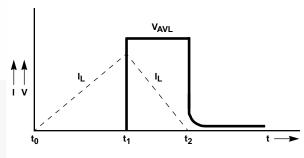
t_{rr} Waveforms and Definitions



Avalanche Energy Test Circuit



Avalanche Current and Voltage Waveforms



Typical Performance Characteristics

Figure 1. Typical Forward Voltage Drop vs. Forward Current

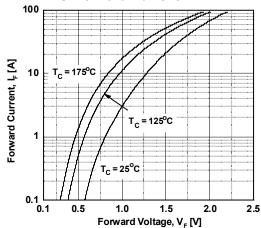


Figure 3. Typical Junction Capacitance

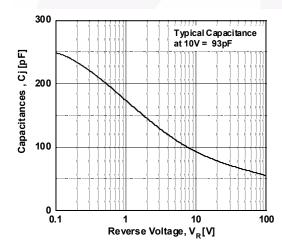


Figure 5. Typical Reverse Recovery Current vs. di/dt

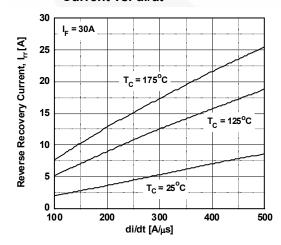


Figure 2. Typical Reverse Current vs. Reverse Voltage

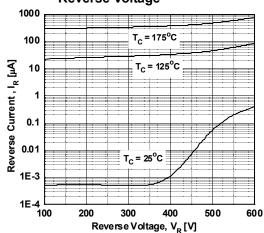


Figure 4. Typical Reverse Recovery Time vs. di/dt

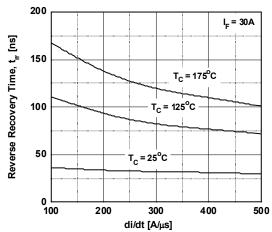
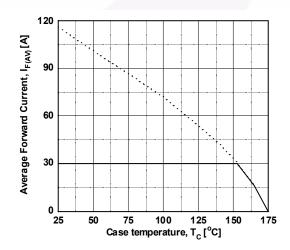


Figure 6. Forward Current Derating Curve



Typical Performance Characteristics (Continued)

Figure 7. Reverse Recovery Charge

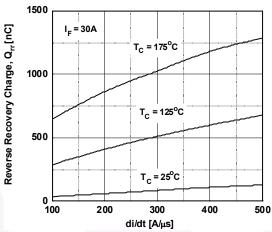
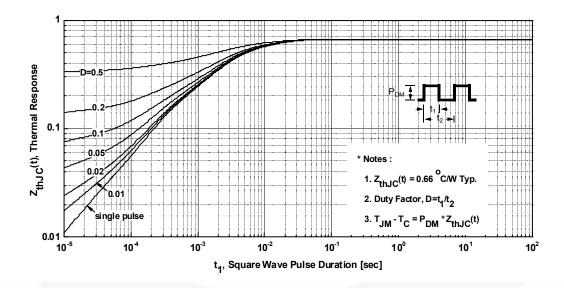
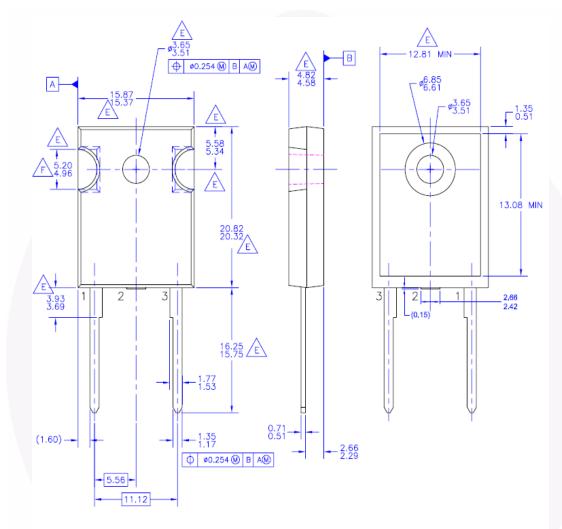


Figure 8. Transient Thermal Response Curve



Mechanical Dimensions

TO-247-2L



NOTES: UNLESS OTHERWISE SPECIFIED

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- C. ALL DIMENSIONS ARE IN MILLIMETERS.
- D. DRAWING CONFORMS TO ASME Y14,5 1994



F. NOTCH MAY BE SQUARE

G. DRAWING FILENAME: MKT-TO247B02_REV02

Dimensions in Millimeters





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